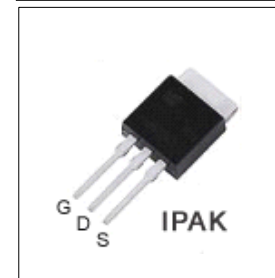
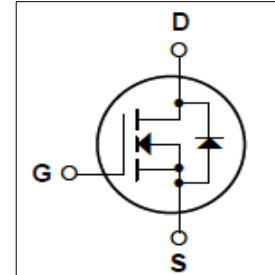


Silicon N-Channel MOSFET

Features

- 6A,700V, R_{ds(on)}(Max 1.5Ω)@V_{GS}=10V
- Ultra-low Gate Charge(Typical 51nC)
- High Current Capability
- 100%Avalanche Tested
- Maximum Junction Temperature Range(150°C)



General Description

This Power MOSFET is produced using Winsemi's advanced planar stripe, This latest technology has been especially designed to minimize on-state resistance, have a high rugged avalanche characteristics. This devices is specially well suited for high efficiency switch mode power supply. electronic Lamp ballasts based on half bridge and UPS.

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V _{DSS}	Drain Source Voltage	700	V
I _D	Continuous Drain Current(@T _c =25°C)	6	A
	Continuous Drain Current(@T _c =100°C)	3.8	A
I _{DM}	Drain Current Pulsed t _p =300us	24	A
V _{GS}	Gate to Source Voltage-Continuous	±30	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	582	mJ
I _S	Source Current (Body Diode)	6	A
P _D	Total Power Dissipation(@T _c =25°C)	120	W
T _J , T _{stg}	Junction and Storage Temperature	-55~150	°C
T _L	Channel Temperature(1/8" from case for 10s)	260	°C

Thermal Characteristics

Symbol	Parameter	Value			Units
		Min	Typ	Max	
R _{QJC}	Thermal Resistance, Junction-to-Case	-	0.96	1.04	°C/W
R _{QJA}	Thermal Resistance, Junction-to-Ambient	-	62.5		°C/W

Electrical Characteristics (Tc = 25°C)

Characteristics	Symbol	Test Condition	Min	Type	Max	Unit	
Gate leakage current	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	-	-	±100	nA	
Gate-source breakdown voltage	V _{(BR)GSS}	I _G = 250μA, V _{DS} = 0 V	±30	-	-	V	
Drain cut-off current	I _{DSS}	V _{DS} =700V, V _{GS} =0V, T _c = 25°C	-	-	10	μA	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 250 μA, V _{GS} = 0 V	700	-	-	V	
Break Voltage Temperature Coefficient	$\frac{\Delta BV_{DSS}}{\Delta T_J}$	I _D =250μA, Referenced to 25°C	-	0.79	-	mV/°C	
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2	-	4	V	
Drain-source ON resistance	R _{DS(ON)}	V _{GS} = 10 V, I _D = 12A	-	-	1.5	Ω	
Forward Transconductance	g _{fs}	V _{DS} = 50V, I _D = 3A	-	4.12	-	S	
Input capacitance	C _{iss}	V _{DS} = 25 V,	-	920	1200	pF	
Reverse transfer capacitance	C _{rss}	V _{GS} = 0 V,	-	45	55		
Output capacitance	C _{oss}	f = 1 MHz	-	100	115		
Switching time	Rise time	tr	V _{DD} = 350 I _D = 6A R _G = 11.5Ω	-	23	55	ns
	Turn-on time	ton		-	18	45	
	Fall time	tf		-	26	60	
	Turn-off time	toff		-	76	160	
Total gate charge (gate-source plus gate-drain)	Q _g	V _{DS} = 560V V _{GS} = 10V	-	51	67	nC	
Gate-source charge	Q _{gs}	I _D = 6A	-	8.3	-		
Gate-drain ("miller") Charge	Q _{gd}		-	23.1	-		

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Type	Max	Unit
Continuous drain reverse current	I _{DR}	-	-	-	6	A
Pulse drain reverse current	I _{DRP}	-	-	-	24	A
Forward voltage (diode)	V _{D_{SF}}	I _{DR} = 6A, V _{GS} = 0 V	-	-	1.5	V
Reverse recovery time	t _{rr}	I _{DR} = 6A, V _{GS} = 0 V, di _{DR} / dt = 100 A / μs	-	440	-	ns
Reverse recovery charge	Q _{rr}		-	4.05	-	μC

- Note 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
 3. L = 30mH, I_{AS} = 6A, V_{DD} = 50V, R_G = 27Ω, Starting T_J = 25°C
 4. I_{SD} ≤ 6A, di/dt ≤ 140A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C

TYPICAL PERFORMANCE CURVES

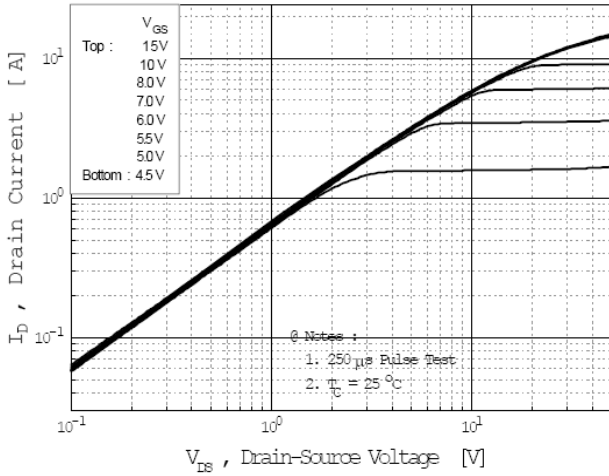


Fig 1. Output Characteristics

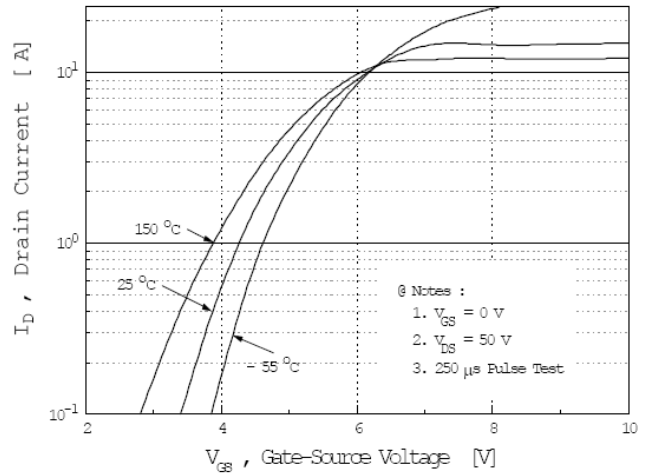


Fig 2. Transfer Characteristics

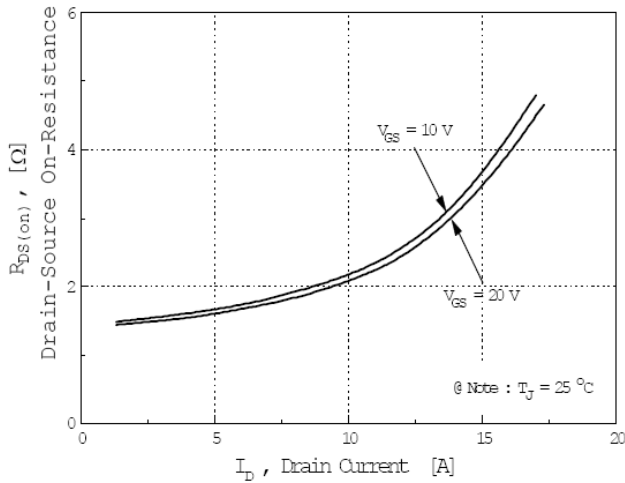


Fig 3. On-Resistance vs. Drain Current

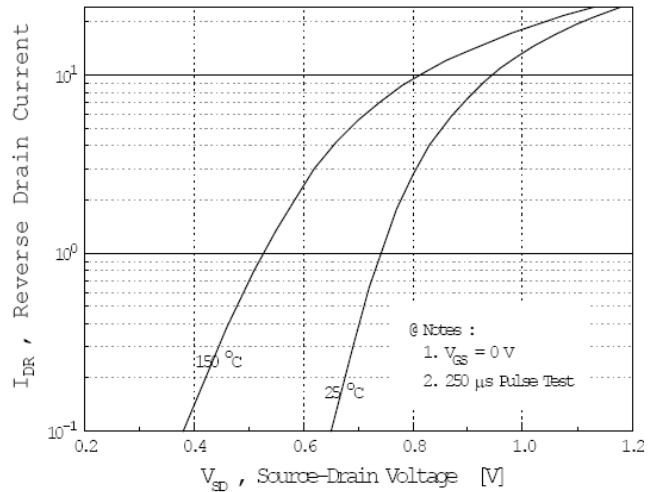


Fig 4. Source-Drain Diode Forward Voltage

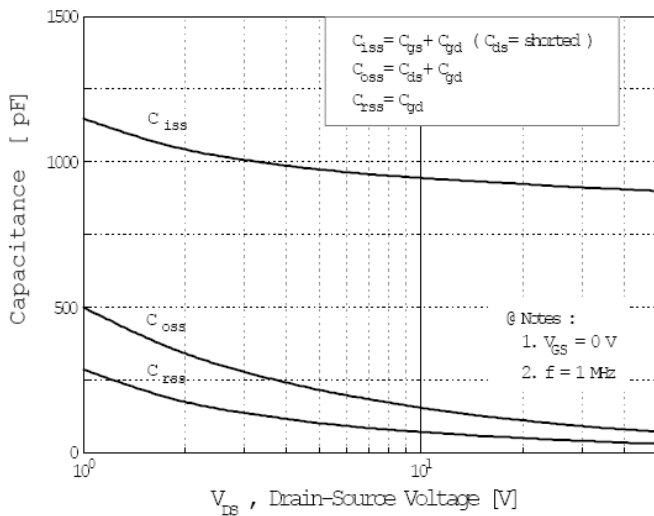


Fig 5. Capacitance vs. Drain-Source Voltage

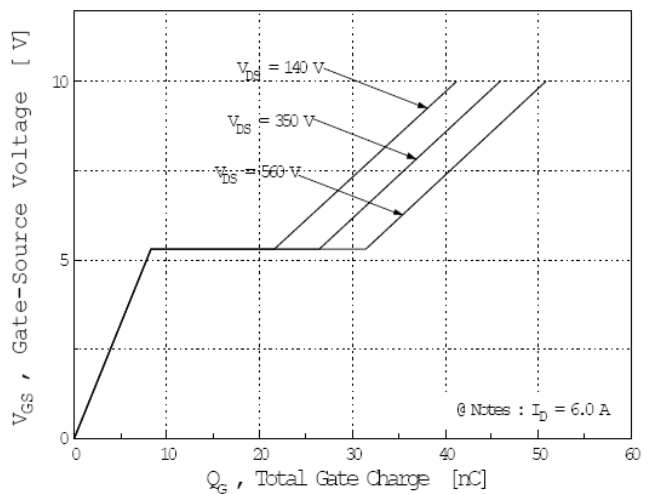


Fig 6. Gate Charge vs. Gate-Source Voltage



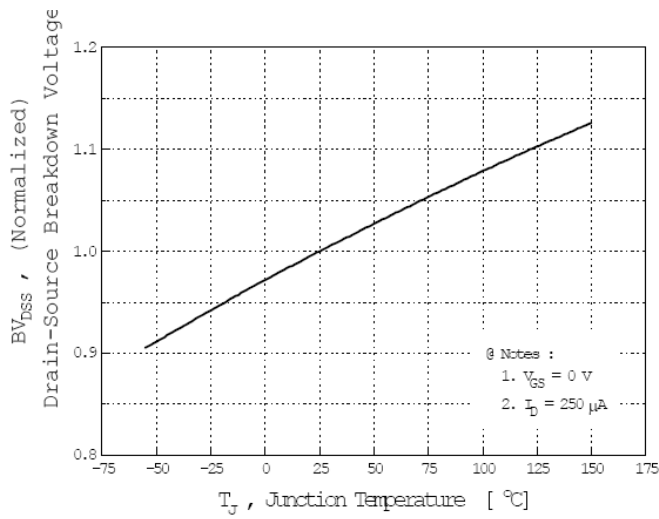


Fig 7. Breakdown Voltage vs. Temperature

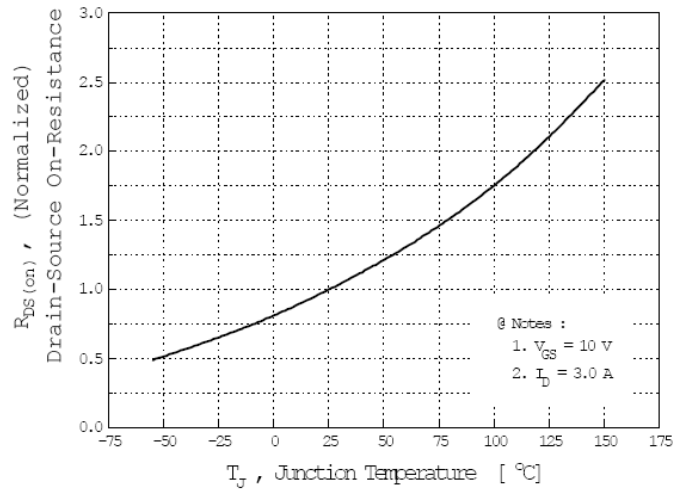


Fig 8. On-Resistance vs. Temperature

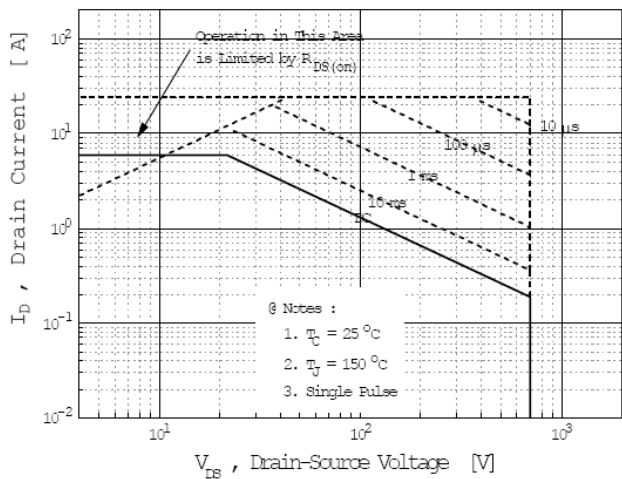


Fig 9. Max. Safe Operating Area

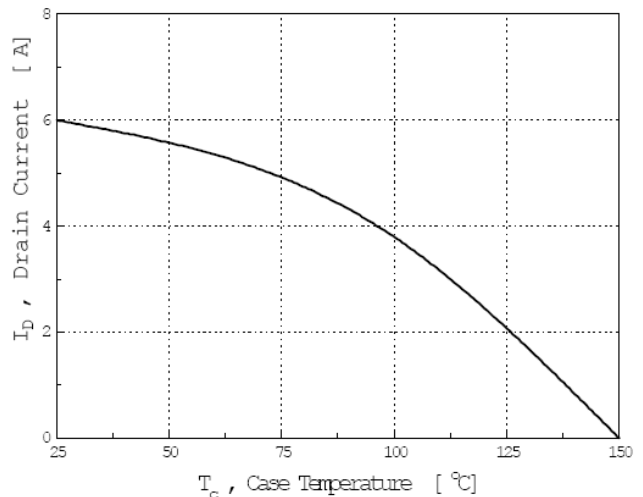


Fig 10. Max. Drain Current vs. Case Temperature

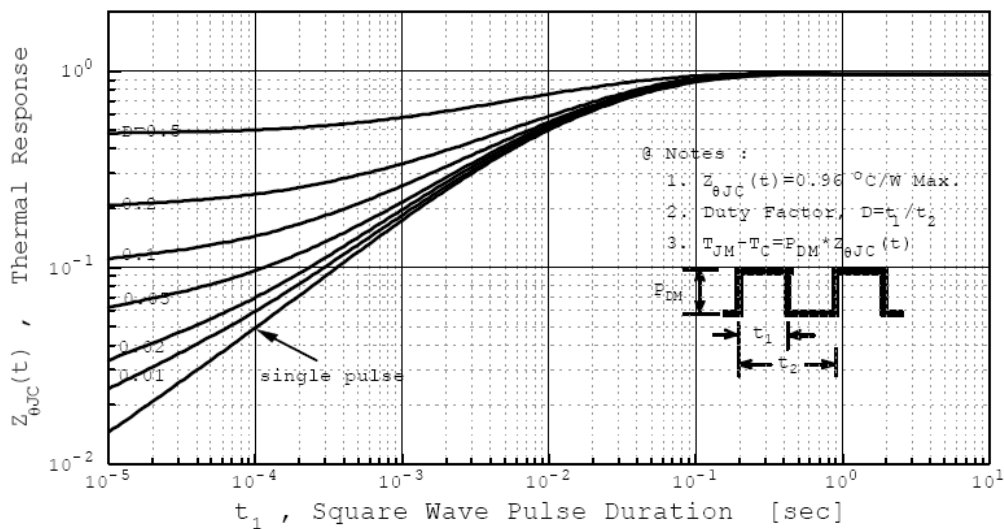
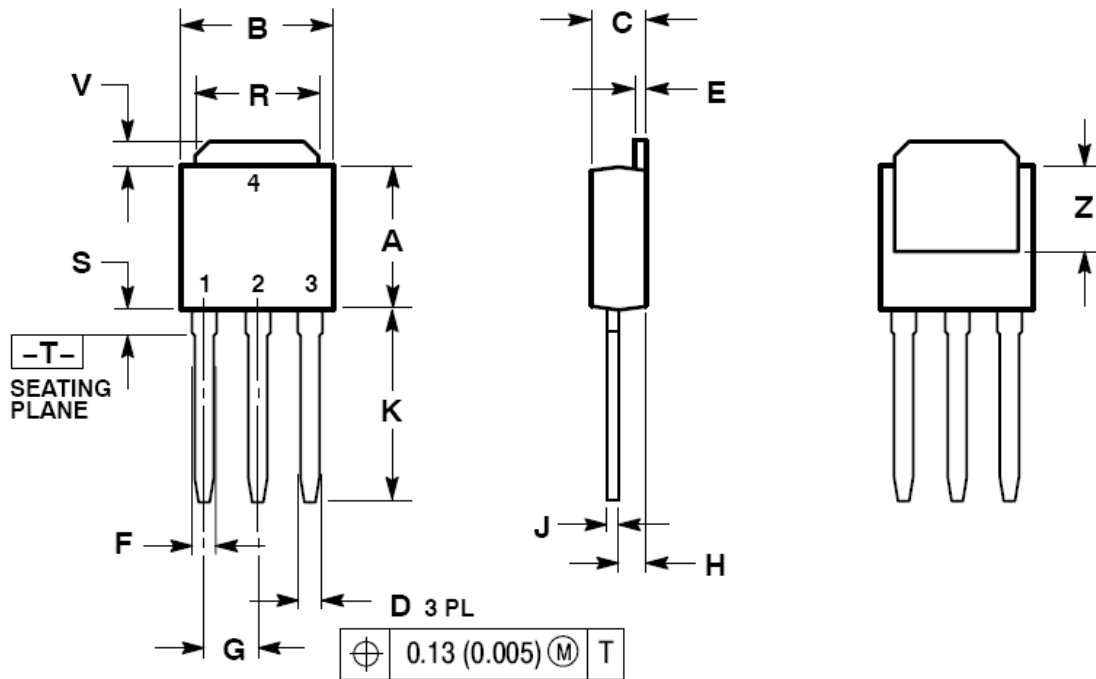


Fig 11. Thermal Response

TO-251 Package Dimension



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
V	0.035	0.050	0.89	1.27
Z	0.155	---	3.93	---

STYLE 2:
 PIN 1. GATE
 2. DRAIN
 3. SOURCE
 4. DRAIN